MT18SD-H-T5

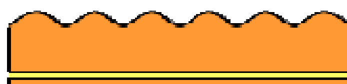
MITSUI KINZOKU

- MicroThin为附18μm载体铜箔的超薄铜箔。
  MicroThin is ultra thin foil with 18μm carrier foil.
- 适用于无芯封装基板的工艺 。
  Suitable for core-less process

用途/Application

- **IC封装载板**
  /Semiconductor Package
- **无芯封装基板**
  /Core-less substrate

构成/Composition



生产地点/Production Site

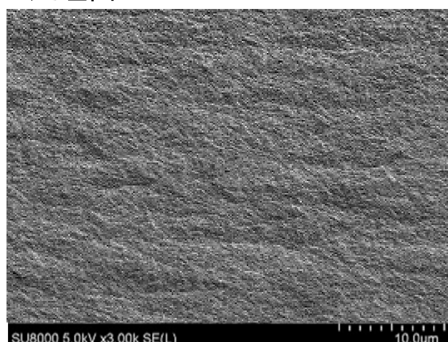
- **日本 / Japan**

代表性特性数据/Representive date

	μm	Area weight (g/m2)	Deposited side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
MT18SD-H-T5	5	40	1	－	－	－

※上述表列为代表性数据非保证值
This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/ resist side